

Patent Abstracts of Japan

PUBLICATION NUMBER : 01245530
PUBLICATION DATE : 29-09-89

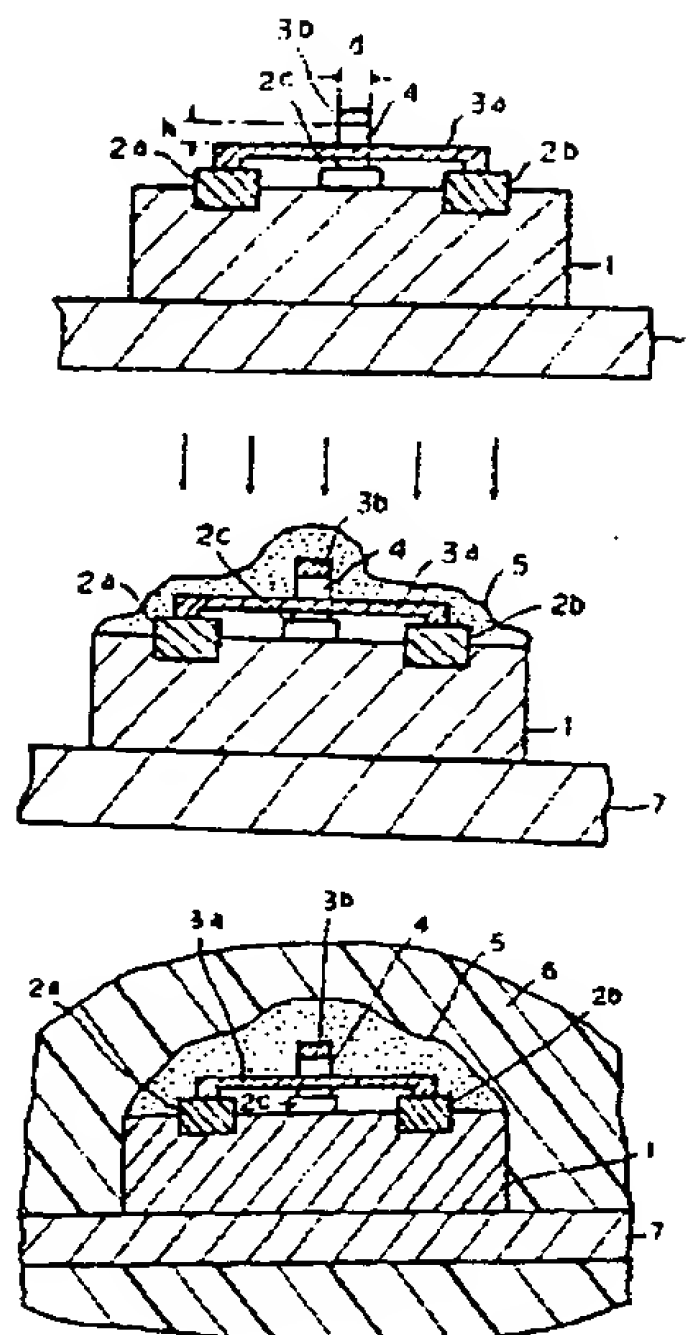
APPLICATION DATE : 28-03-88
APPLICATION NUMBER : 63073996

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INT.CL. : H01L 21/56 H01L 21/90 H01L 21/95
H01L 23/30

TITLE : METHOD OF PACKAGING
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To package a semiconductor device by resin molding process doing no damage to the function thereof as well as to disuse the ceramic case for cutting down the manufacturing cost by a method wherein the passivation process to cover the air bridge inner wiring part with an inert film is performed by the ECR plasma CVD process and then said semiconductor device is molded out of resin.

CONSTITUTION: The whole surface of an air bridge inner wiring part is covered with an inert film 5 formed by ECR plasma CVD process. This ECR plasma CVD process is performed by setting up the direction of the magnetic field so as to make a right angle with the surface (inner wiring part) of a substrate 1. At this time, a material produced from the inert film is pored on the substrate surface in the rectangular direction so that said material may not permeate into the parts below respective wirings 3a, 3b. Thus, said material does not permeate into the parts directly below the wirings 3a, 3b where the parasitic capacity is most liable to be increased so that any spaces may be sectioned. Consequently, another space 4 isolated from outer parts by the inert film 5 can be secured at the junction of the upper wiring 3b and the lower wiring 3a. Finally an inert semiconductor device is molded out of resin to finish the packaging process.

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